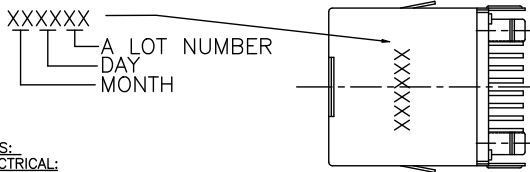
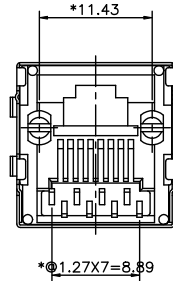
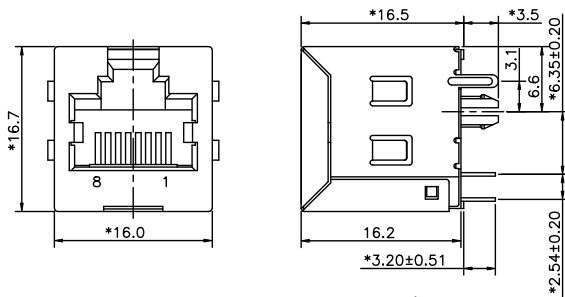


DIRFRD006

REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD
△		Modify Drawing	02/23/93	
△		MODIFY DRAWING	10/22/94	
△		ADD PART NO	01/23/95	



NOTES:

ELECTRICAL:

- VOLTAGE RATING : 125 VAC RMS.
- CURRENT RATING : 1.5 AMP.
- CONTACT RESISTANCE : 30 MILLIOHMS MAX.
- INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 500 VDC.
- DIELECTRIC STRENGTH : 1000 VAC RMS 60Hz, 1MIN.

MECHANICAL:

- HOUSING MATERIAL : GLASS FILLED POLYESTER UL94V-0.
- CONTACT MATERIAL : PHOSPHOR BRONZE t=0.35mm.
- PLATING : GOLD PLATING OVER NICKEL.
- OPERATING LIFE : 750 CYCLES MIN.
- PCB RETENTION PRE-SOLDER : 1 LB MIN.
- PCB RETENTION POST-SOLDER: 10 LBS MIN.

ENVIRONMENTAL:

- STORAGE : -40°C TO +85°C.
- OPERATION: -40°C TO +85°C.

MATES WITH MODULAR PLUG CONFORMING TO FCC PART 68, SUBPART F.

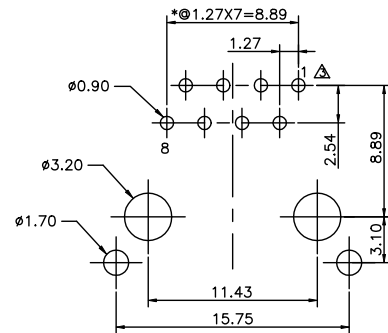
CUL FILE NO. E163191

PART NUMBER: E52D8-RXOX4X

- | | |
|-------------------|------------------|
| △ SHIELD PLATING: | GOLD PLATING: |
| 1- TIN PLATING | 1- 3u" 2- 6u" |
| 2- NICKEL PLATING | 3- 15u" 4- 30u" |
| | 5- 50u" |
| | 0-PBT+15%GF(BK) |
| | 1-PBT+30%GF (BK) |

△ LEAD-FREE PART NUMBER: E52D8-RXOX4X-L

- | | |
|-------------------|------------------|
| △ SHIELD PLATING: | GOLD PLATING: |
| 1- TIN PLATING | 1- 3u" 2- 6u" |
| 2- NICKEL PLATING | 3- 15u" 4- 30u" |
| | 5- 50u" |
| | 0-PBT+15%GF(BK) |
| | 1-PBT+30%GF (BK) |
| | △ B-FR52 BK |



PC Board Layout Component Side Shown

DIMENSIONS		DATE		TITLE	
MM (INCH)	DFTO BASS	DATE	7/8/97	FULL RISE ELECTRONIC CO., LTD	
TOLERANCES EXCEPT AS NOTED	CHKD SHAWY	DATE	2005/1/5	TITLE	
MM	INFO	DATE		RJ45 TOP ENTRY PCB MODULAR JACK(DIP TYPE)	
±	APPROVALS/HSG	DATE	2005/1/5	DRAWING NO. GE523070	
±	MATERIAL :			/PART NO. SEE NOTE	
±	QT'Y :			DO NOT SCALE DRAWING	
±	FINISH :			SHEET X OF Y	
±	SCALE : 3:1			SIZE A3	
THIRD ANGLE PROJECTION					REV 3

8 | 7 | 6 | 5 | 4 | 3 | 2 | 1

H
G
F
E
D
C
B
A